



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D
<i>* : Required Field</i>			


Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2015-10-06
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	IPD MD CHAMPION
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
<b>Legal Statement</b>	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	SBVU*C20C2GC	A	Z45A	2015-10-06
	Amount	UoM	Unit type	ST ECOPACK Grade
	4550.00	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
NAC	NAC	NAC		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	15.3X12.63X4.5	3	Through-hole	
Comment	Package: TOP3 NO ISOL. MD valid for CP BTB26-600BRG			

QueryList : ROHS directive 2011/65/EU \_ July 2011

Query		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
5 - Product(s) is obsolete, no information is available		false
6 - Product(s) is unknown, no information is available		false
Exemption Id.	Description	
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)	
7c-I	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound	

QueryList : REACH-15th June 2015

Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	SBVU*C20C2GC					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	16.606	mg	supplier	die	Silicon (Si)	7440-21-3		13.980	mg	841864	3073
				supplier	metallization	Nickel (Ni)	7440-02-0		1.000	mg	60219	220
				supplier	metallization	Gold (Au)	7440-57-5		0.100	mg	6022	22
				supplier	back side metallization	Gold (Au)	7440-57-5		0.018	mg	1084	4
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.380	mg	22883	84
				supplier	glass coating	Glass : Aluminium Oxide	1344-28-1		0.113	mg	6805	25
				JIG - R	glass coating	Lead-Borate Glass	65997-18-4	7c-I-Electrical and e	1.015	mg	61122	223
				Supplier	alloy	Copper (Cu)	7440-50-8		3229.070	mg	997278	709686
Leadframe	Copper & its alloys	3237.882	mg	Supplier	alloy	Iron (Fe)	7439-89-6		1.488	mg	460	327
				Supplier	alloy	Iron Phosphide (FeP)	26508-33-8		2.716	mg	839	597
				Supplier	alloy	Nickel (Ni)	7440-02-0		4.608	mg	1423	1013
				JIG - R	Lead/Lead Compounds	Lead (Pb)	7439-92-1	7a. Lead in high me	44.447	mg	934998	9769
Die Attach	Solder	47.537	mg	Supplier	soft solder	Silver (Ag)	7440-22-4		0.713	mg	14999	157
				Supplier	soft solder	Tin (Sn)	7440-31-5		2.377	mg	50003	522
				Supplier	Moulding compound	Silica, vitreous	60676-86-0		939.467	mg	760000	206476
Encapsulation	Other inorganic materials	1236.140	mg	Supplier	Moulding Compound	Phenol resin	9003-35-4		74.168	mg	60000	16301
				Supplier	Moulding Compound	Carbon black	1333-86-4		9.889	mg	8000	2173
				Supplier	Moulding Compound	Epoxy Cresol Novolak	29690-82-2		126.086	mg	102000	27711
				Supplier	Moulding Compound	Metal hydroxide	21645-51-2		24.723	mg	20000	5434
				Supplier	Moulding Compound	Others	Proprietary		61.807	mg	50000	13584
Finishing	Other inorganic materials	11.835	mg	Supplier	connection coating	Tin (Sn)	7440-31-5		11.835	mg	1000000	2601